

Title (en)  
Lamp assembly heater and base

Title (de)  
Heizvorrichtung und Sockel für eine Lampenanordnung

Title (fr)  
Dispositif de chauffage et culot pour un agencement de lampe

Publication  
**EP 0872876 A1 19981021 (EN)**

Application  
**EP 98107048 A 19980417**

Priority  
US 84450797 A 19970418

Abstract (en)  
A lamp assembly is provided which includes a lamp (12) a lamp base (14) attached to the lamp (12), and a lamp heater. One or more abutment regions of the lamp (12) and the lamp base (14) mate with one another to provide axial and rotational orientation of the lamp (12) relative to the lamp base (14). The lamp heater conforms to the surface of the lamp (12) and may be bonded thereto by an adhesive. The lamp heater may include a heater element (16) and thermistor (18) adjacent to a surface of the lamp (12). The lamp (12), lamp heater and thermistor (18) are connected to a connector (22). A thermal breaker (20) is connected to the heater. The thermal breaker (20) provides a safety device to control maximum lamp temperature. The thermistor (18) controls the operating temperature of the lamp (12). The lamp assembly may include a display device (220) wherein the lamp (12) is secured to the display device (220). <IMAGE>

IPC 1-7  
**H01J 61/52; H01J 5/54**

IPC 8 full level  
**F21V 25/10** (2006.01); **H01J 5/54** (2006.01); **H01J 61/52** (2006.01)

CPC (source: EP)  
**H01J 5/54** (2013.01); **H01J 61/52** (2013.01)

Citation (search report)

- [XAY] US 5616989 A 19970401 - TAILLIE JOSEPH P [US], et al
- [XA] PATENT ABSTRACTS OF JAPAN vol. 005, no. 198 (E - 087) 16 December 1981 (1981-12-16)
- [XAY] PATENT ABSTRACTS OF JAPAN vol. 013, no. 016 (E - 703) 13 January 1989 (1989-01-13)
- [XAY] DATABASE WPI Section EI Week 9442, Derwent World Patents Index; Class S02, AN 94-336076, XP002072595
- [XA] PATENT ABSTRACTS OF JAPAN vol. 097, no. 003 31 March 1997 (1997-03-31)
- [YA] PATENT ABSTRACTS OF JAPAN vol. 095, no. 009 31 October 1995 (1995-10-31)
- [YA] PATENT ABSTRACTS OF JAPAN vol. 018, no. 551 (E - 1619) 20 October 1994 (1994-10-20)
- [YA] PATENT ABSTRACTS OF JAPAN vol. 010, no. 259 (E - 434) 4 September 1986 (1986-09-04)

Cited by  
WO2010063723A1; US8614425B2; US9789427B2

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